



NESPER
Shaping progress.



Contact Pads

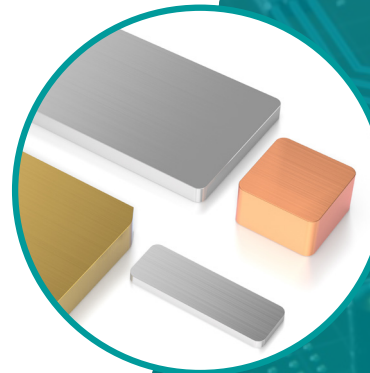
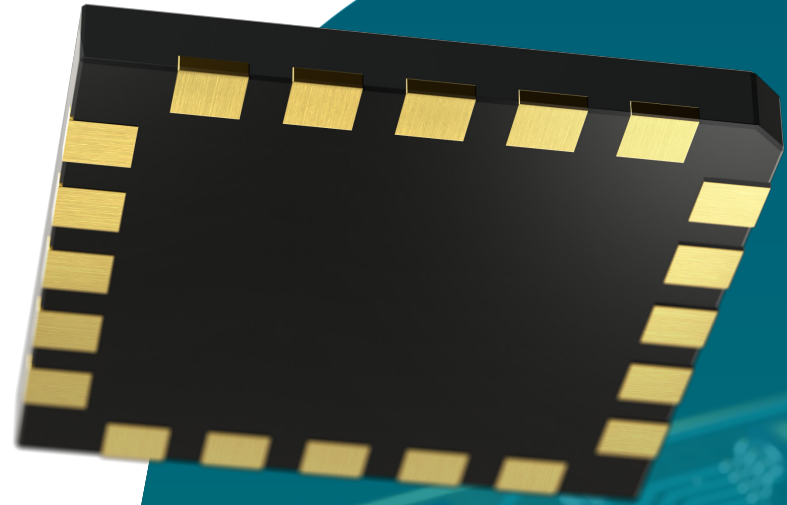
PRECISION ENGINEERED TO PERFECTION

[MORE INFORMATION](#)

Applications

Our contact pads deliver outstanding performance across a wide range of demanding applications:

- Cooling pads / heat sinks
- Sinter pads
- Solder pads
- Bond pads
- Electrical contacting of chips, MOSFETs & power FETs
- Chip packaging: Land Grid Array (LGA) pads
- Spacer elements
- PCB assembly



Technical Capabilities & Specifications

Manufactured to your exact specifications, engineered for your application.

Available in a wide range of designs, materials and surface finishes:

- **Edge lengths from 0.2 to 5.0 mm**
- **Extremely tight tolerances,**
e.g. flatness < 10 µm – maximizing contact areas and ensuring long-term, reliable electrical connections
- **Ferrous and non-ferrous capabilities,**
including Cu alloys and FeNi42
- **Electroplated surface finishes**
such as silver (Ag), gold (Au) or nickel (Ni)
- **Flexible packaging options:**
bulk, tape & reel, or more

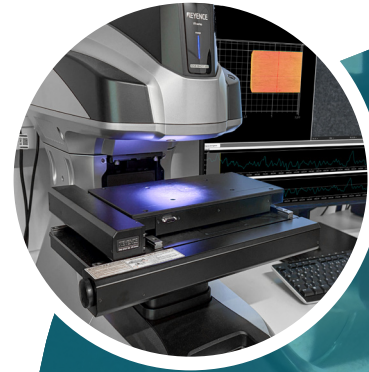


Innovative Manufacturing Process

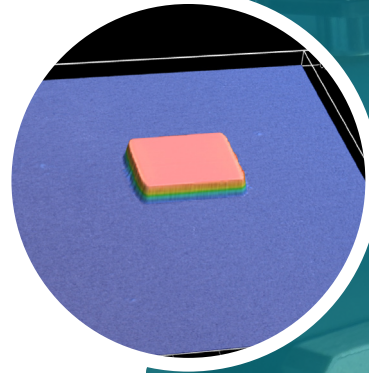
At NESPER, innovation is more than a buzzword.

Our emphasis on intelligent automation and modern production processes sets the bar for quality, efficiency and cost-effectiveness:

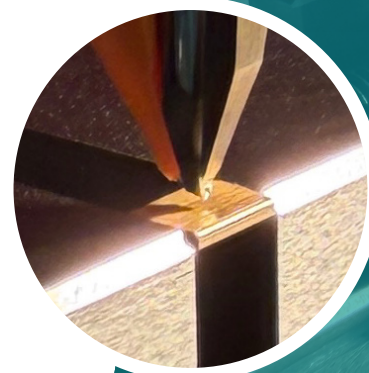
- **Continuous investment in forward-thinking ideas,** emerging technologies, and smarter processes, ensuring top-tier process stability and consistency.
- **Able to leverage high-tech manufacturing and engineering expertise toward advanced design analysis and material optimization,** minimizing scrap and maximizing yield.
- **We get it right the first time,** no secondary finishing required
- **Delivering uncompromising quality at scale,** by transforming complex production challenges into streamlined, repeatable excellence.
- **Attractive, internationally competitive pricing** with genuine “Made in Germany” quality
- **Advanced quality control systems** including in-house bondability testing and 3D surface inspection



3D surface inspection



3D scan representation



In-house Bond testing



ABOUT NESPER

Founded in 1956, NESPER remains 100% family-owned to this day.

A commitment to stability, reliability, and emphasis on long-term partnership and prosperous collaboration.

For seven decades, we have been developing and manufacturing high-precision, dependable, and cost-efficient components across many demanding industries. This extensive, versatile expertise makes us a strong partner for your future projects, regardless of market.

Our headquarters and flagship manufacturing site are located in **Ispringen near Pforzheim, Germany**. Our North American expansion, a second production facility in **LaGrange, Georgia (USA)**, enables us to support our customers and their diverse markets worldwide.

GERMANY

Egon Nesper GmbH & Co. KG

Industriestraße 16-20

D-75228 Ispringen

Phone: +49 7231 88670-0

info@nesper.com

USA

Nesper International, Inc.

107 Wiley Road

LaGrange, GA 30240

Phone: +1 (706) 812 1966

Fax: +1 (706) 812 1972

usa@nesper.com

[NESPER.COM](https://www.nesper.com)

